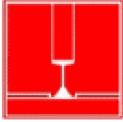

Adhesive for chip mounting machines

Seal-glo NE series

We developed “Seal-glo NE series ”adhesive for chip mounting machines or SMD.
They are one-part thermo-setting epoxy adhesive with the property of preservation stability, and are of 1 to 2 minute short time or high speed curability required for 120 to 150℃ heat-give SMD packaging.
We are ready, in addition, to offer the adhesive of various grades with excellent micro-printability or with suitability for high-speed dispensers.

■ *Seal-glo* NE8800T

■Advantages

① Much lower temperature curing is practically performed.

② Very good stable curing shapes without stringing and slumping at super high speed dispensing and pretty small dots.

③ Stable adhesive strength can be obtained with a variety of SMD.

④ Long-heat preservation stability is expected.

⑤ High-heat resistively and excellent electric property are processed of.

■Curing condition

Recommended curing condition;

- The recommended curing condition is; 60 sec. after PCB’s surface temperature has reached 150℃ or 90 sec. after the said temperature has come up 120℃.
  The higher temperature given is and the longer time applied is, the stronger adhesive strength would be obtained.
- A suggestion is that an optimum series of curing condition should be searched out, for the temperatures exerted on dispensed adhesive may occasionally vary according to the sizes, the lay-out, etc. of component parts to mount on PCB’s.

■*Seal-glo* NE3000Ｓ

■Advantages

We developed “***Seal-glo*** NE3000S”, a thermo-setting single component epoxy adhesive, for chip mounting machines, especially screen printing machines.

1）With a variety of SMD,stable adhesiveness can be obtained.

2）On account of proper viccosity value and thixo retio for screen printing, no spreading of printing patterns is likely to occur.

3）Being a single part adhesive, it has excellent stability against a long period of storage time.

4）Having high green strength, no skewing of chips under high speed mounting will take place.

■Specifications/ *Seal-glo* NE8800T&NE3000S

		ＮＥ8800T	ＮＥ3000Ｓ
Composition		Epoxy resin	
Appearance		Paste/red-colored	
Specific gravity		1.28	1.38
Viscocity at 25℃,5rpm		300,000mPa・S(300.000cps)	390Pa・S(390.000cps)
Adhesive strength	2125c	44N(4.5kgf)	38N(3.9kgf)
	Mini-mold tr	45N(4.6kgf)	38N(3.9kgf)
	SOP-IC 16P	92N(9.4kgf)	92N(9.4kgf)
Electric property Volume resistance Insulation resistance Initial value		2.6×10^{16}Ω・cm 1.0×10^{14}Ω 1.2×10^{12}Ω	1.8×10^{17}Ω・cm 3.4×10^{14}Ω.cm 2.1×10^{32}Ω.cm

After treating＊ Dielectric constant Dielectric loss tangent	3.62/1MHz 0.013/1MHz	3.8（100KHz） 0.027（100KHz）
Preservation condition	Keep in refrigerator below 2℃～10℃	